TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSVI)

## **TPC8124**

# Lithium Ion Battery Applications Power Management Switch Applications

Unit: mm

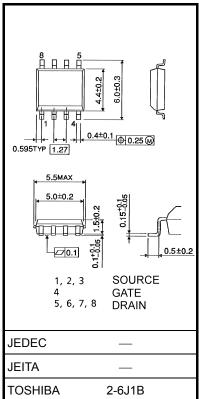
- Small footprint due to small and thin package
- Low drain-source ON-resistance:  $RDS(ON) = 6.1 \text{ m}\Omega \text{ (typ.)}$
- Low leakage current:  $I_{DSS} = -10 \,\mu A \,(max) \,(V_{DS} = -40 \,V)$
- Enhancement mode:  $V_{th} = -0.8$  to -2.0 V ( $V_{DS} = -10$  V,  $I_{D} = -0.5$ mA)

#### **Absolute Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	-40	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	-40	V
Gate-source voltage		$V_{GSS}$	-25/+20	V
Drain current	DC (Note 1)	ΙD	-12	Α
Dialii Cuitelii	Pulse (Note 1)	$I_{DP}$	-48	^
Drain power dissipatio	n (t = 10 s) (Note 2a)	$P_{D}$	1.9	W
Drain power dissipatio	n (t = 10 s) (Note 2b)	$P_{D}$	1.0	W
Single pulse avalanch	e energy (Note 3)	E <sub>AS</sub>	134	mJ
Avalanche current	(Note 1)	I <sub>AR</sub>	-12	Α
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature r	ange	T <sub>stg</sub>	-55 to 150	°C

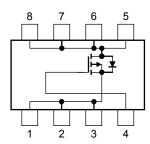
Note 1, Note 2, Note 3: See the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum



Weight: 0.080 g (typ.)

#### **Circuit Configuration**



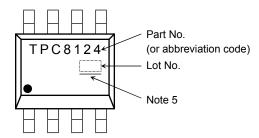
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

#### **Thermal Characteristics**

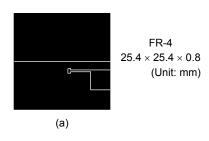
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

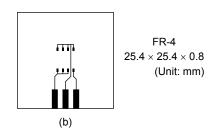
#### Marking (Note 4)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a)Device mounted on a glass-epoxy board (a) (b)Device mounted on a glass-epoxy board (b)

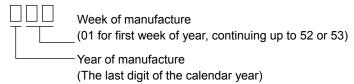




Note 3:  $V_{DD} = -24$  V,  $T_{ch} = 25$  °C (initial), L = 1.0 mH,  $R_G = 25$   $\Omega$ ,  $I_{AR} = -12$  A

Note 4: • on lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



Note 5: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

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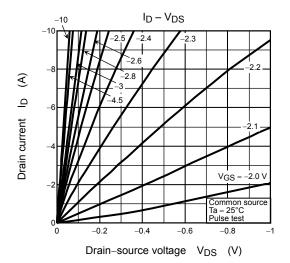
## Electrical Characteristics (Ta = 25°C)

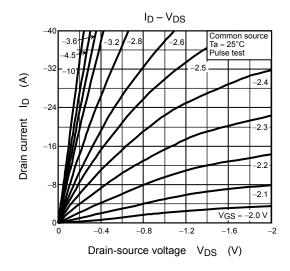
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curre	ent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
Drain cut-OFF curr	ent	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain aguras broad	rdown voltage	V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-40	_	_	V
Drain-source break	down voitage	V <sub>(BR) DSX</sub>	$I_D = -10 \text{ mA}, V_{GS} = 10 \text{ V}$ (Note 6)	-30	-30     —       -0.8     —       -2.0       —     7.7       10       —     6.1       8       —     4750       —     540		v
Gate threshold vol	age	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -0.5 \text{ mA}$	+ +		-2.0	V
Drain-source ON-re	naiatanaa	D= 0 (01)	$V_{GS} = -4.5 \text{ V}, I_D = -6 \text{ A}$	_	7.7	10	- mΩ
Drain-source ON-1	esisiance	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -6 \text{ A}$	_	6.1	8	
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	4750	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	540	_	
Output capacitance		Coss		_	620	_	
	Rise time	t <sub>r</sub>	V <sub>GS</sub> 0 V 7	_	9	_	- ns
Switching time	Turn-ON time	t <sub>on</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz  V <sub>GS</sub> -10 V    D = -6 A   O V   O   O   O   O   O   O   O   O	_	- ±100 - 10 -40	_	
Switching time	Fall time	t <sub>f</sub>	4.7.5 3.4	_	110	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \approx -20 \text{ V}$ Duty ≤ 1%, $t_W = 10 \text{ μs}$	_	390	_	
Total gate charge (gate-source plus (	gate-drain)	Qg	V <sub>DD</sub> ≈ -32 V, V <sub>GS</sub> = -10 V,	_	104	104 —	
Gate-source charge 1		Q <sub>gs1</sub>	$I_D = -12 \text{ A}$	_	10	_	nC
Gate-drain ("miller"	Gate-drain ("miller") charge			_	27	_	

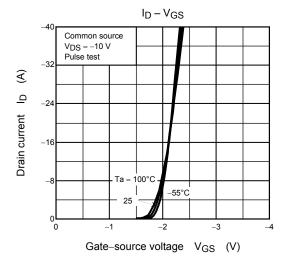
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

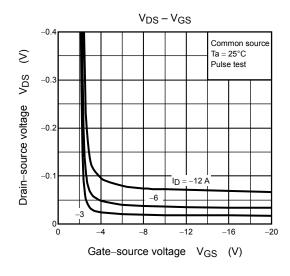
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-48	А
Forward voltage (diode)		V <sub>DSF</sub>	I <sub>DR</sub> = -12 A, V <sub>GS</sub> = 0 V	_	_	1.2	V	

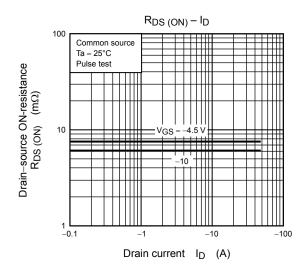
Note 6: VDSX mode (the application of a plus voltage between gate and source) may cause decrease in maximum rating of drain-source voltage.



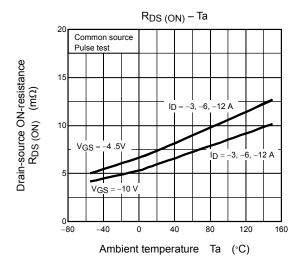


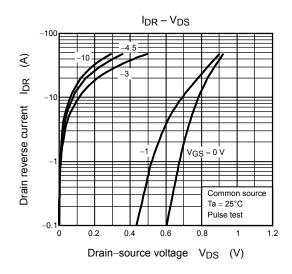


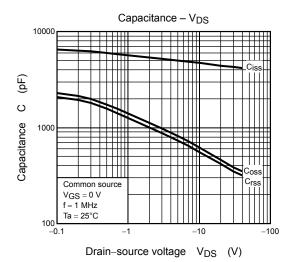


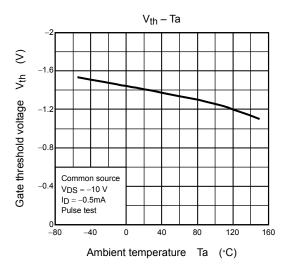


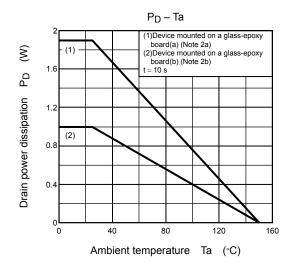
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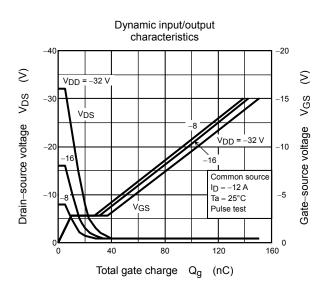




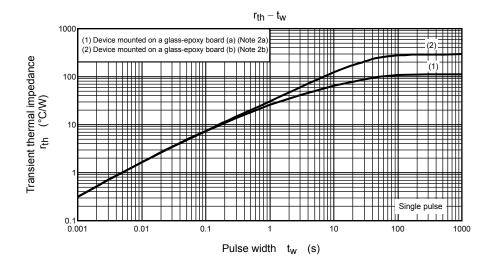


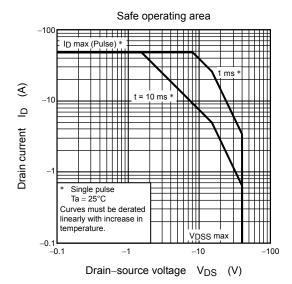






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